



- △1 Substrate: 0.0625"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating
- △2 Pins: Material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.).
- △4 Leads: material- BeCu Alloy 194; plating- 60/40 SnPb (150-400µ")
- △5 Test points: material- Phosphor Bronze; plating- Sn over 50µ" Ni. Gold flash on contact end.

Description: CARRIER ADAPTOR
 TSOP ZIF socket with test points to 26 position TSOP surface-mountable foot. Mini Grid Array (MGA) interface provides plugability between two halves.

All tolerances: ±0.005" (unless stated otherwise). Materials and specifications are subject to change without notice.

CA-SO26D-Z-J-T-01 Drawing	Status: released	Scale: 2:1	Rev: A
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	Drawing by: P. LeBeau	Modified:	
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